

Features

- DC to 2.2 GHz
- Terminals for PCB placement
- Low VSWR
- Aluminum Nitride ceramic
- High power
- RoHS compliant*

Applications

- RF amplifiers
- Attenuators
- Antenna feeds
- Wilkinson dividers

CHF2010xNP Series 10 W Power RF Chip Termination/Resistor

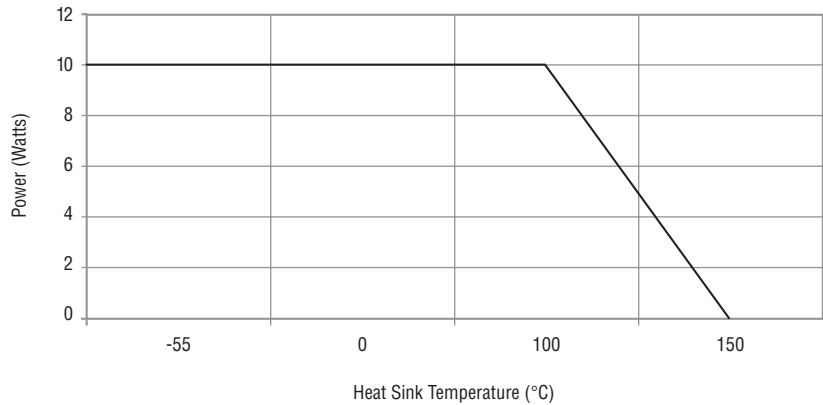
General Specifications

Substrate	ALN
Resistive Film	Thick-Film
Terminals	NiAu
Capacitance	0.75 pF
Resistance	
CHF2010CNP500L	50 Ω
CHF2010CNP101R	100 Ω
CHF2010DNP101R	100 Ω
Tolerance	
CHF2010CNP500L	±5 %
CHF2010CNP101R	±5 %
CHF2010DNP101R	±2 %
Packaging	
Tape & Reel	2000 pcs./10 " reel
Bulk	100 pcs./bag

Absolute Ratings

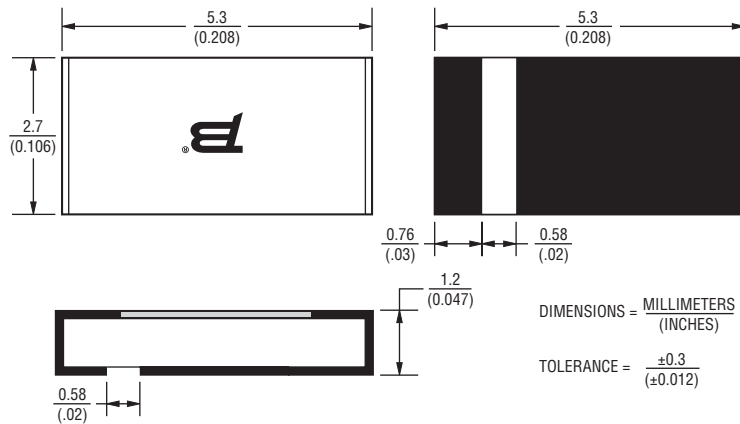
Power	10 W
Frequency	
CHF2010CNP500L	2 GHz
CHF2010CNP101R	2.2 GHz
CHF2010DNP101R	2.2 GHz
VSWR	1.2 Maximum

Characteristic Curve

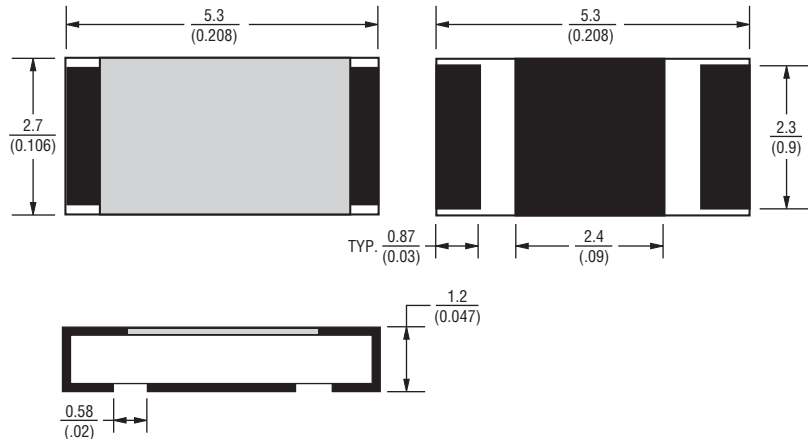


Product Dimensions

CHF2010CNP500L



CHF2010CNP101R & CHF2010DNP101R



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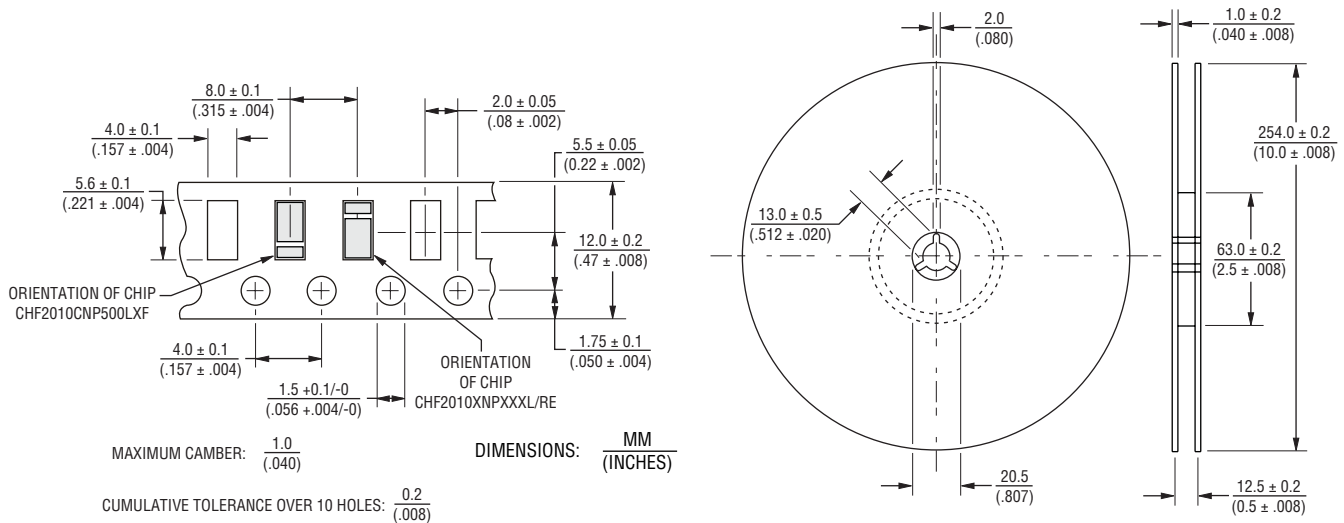
www.bourns.com

*RoHS Directive 2002/95/EC Jan 27, 2003 including Annex.
Specifications are subject to change without notice.
Customers should verify actual device performance in their specific applications.

CHF2010xNP Series 10 W Power RF Chip Termination/Resistor

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Packaging Dimensions



How to Order

CHF 2010 C N P 500 L X E

Model _____
 Package _____
 Version _____
 C = 5 % Tolerance
 D = 2 % Tolerance
 Substrate _____
 Mount _____
 P = Printed Circuit Board
 Resistance Code _____
 500 = 50 Ohm
 101 = 100 Ohm
 Type _____
 L = Termination (One Lead)
 R = Resistor (Two Leads)
 Plating _____
 X = NiAu
 Packaging _____
 Blank = Bulk (100 pcs./bag)
 E = Tape & Reel (2,000 pcs./10 " reel, Orientation of Input Terminal Away from Sprocket)
 *F = Tape & Reel (2,000 pcs./10 " reel, Orientation of Input Terminal Facing from Sprocket)

*Packaging Option F is only available on CHF2010CNP500LXF.

REV. 11/10

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